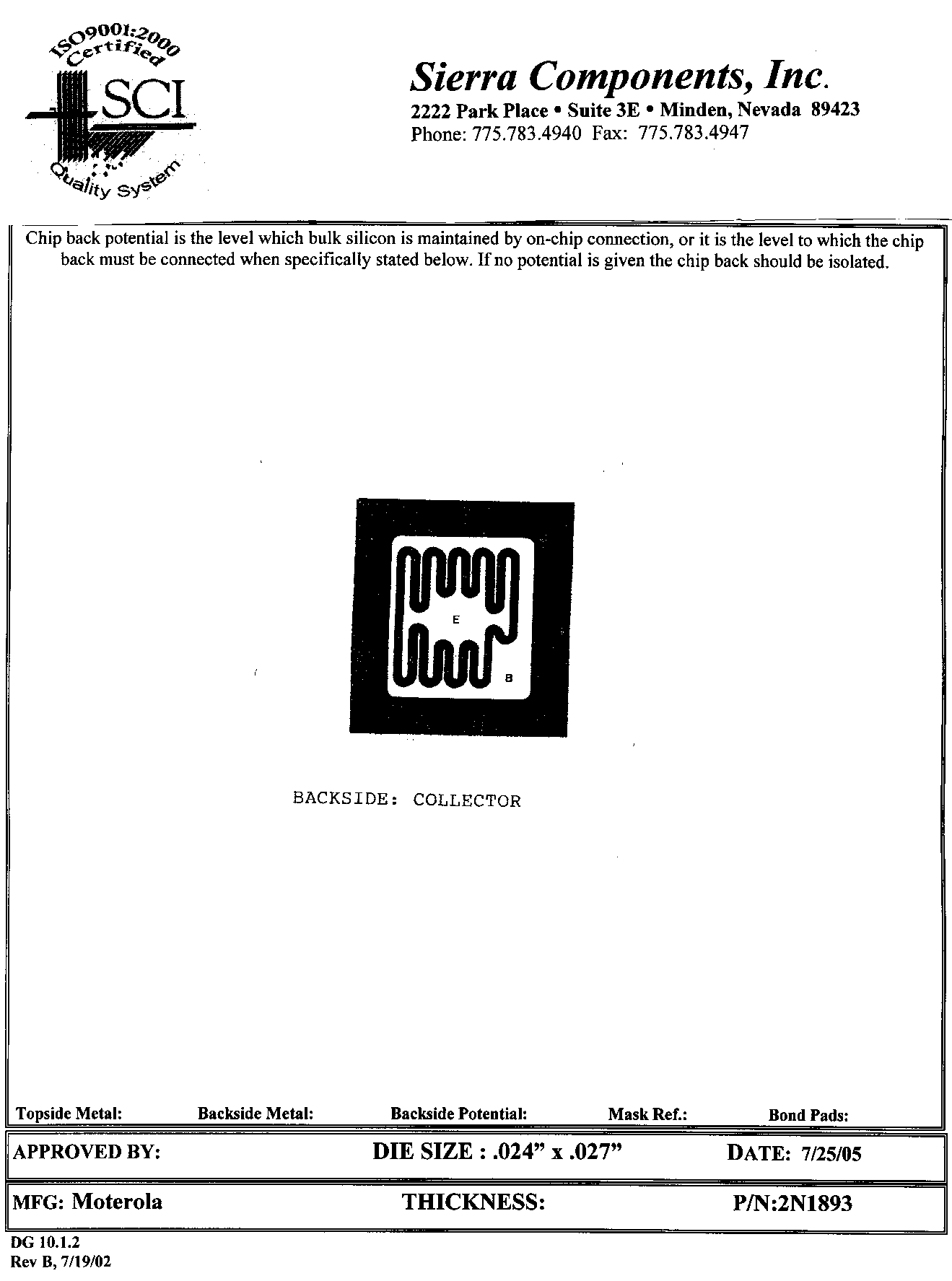
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTIONS:**

1. **V IN**
2. **V OUT**
3. **V OUT**
4. **SENSE**
5. **ADJUST**

**.024”**



**.027**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004 X .006”**

**Backside Potential: COLLECTOR**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .024” X .027” DATE: 1/26/22**

**MFG: MOTOROLA THICKNESS .006” P/N: 2N1893**

**DG 10.1.2**

#### Rev B, 7/1